



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/388,031

Filed: September 1, 1999

For: METALLIZATION STRUCTURES
FOR SEMICONDUCTOR DEVICE
INTERCONNECTS, METHODS FOR
MAKING SAME, AND
SEMICONDUCTOR DEVICES
INCLUDING SAME

Examiner: E. Lee

Group Art Unit: 2815

Attorney Docket No.: 3442US (96-428)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231

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Debra L. Mitchell

Typed/printed name of person whose signature is contained above

AMENDMENT UNDER 37 C.F.R. §1.116

Box AF
Commissioner for Patents
Washington, D.C. 20231

Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed September 26, 2001, the three-month shortened statutory period for response to which expires on December 26, 2001. This response is submitted on or before two months from the mailing date of the Final Office Action.